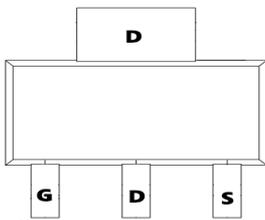




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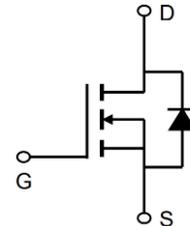
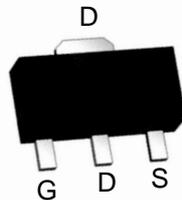
N-Channel Enhancement Mosfet

| | |
|--|--|
| <p>General Description</p> <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM | <p>General Features</p> <p>$V_{DS}=60V$ $I_D=15A$</p> <p>$R_{DS(ON)} = 30m\Omega$ (Typ.) @ $V_{GS}=10V$</p> <p>100% UIS Tested 100% R_g Tested</p>  |
|--|--|



Marking: 15N06

SI:SOT-89-3L



Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

| Symbol | Parameter | Rating | Units |
|------------------------|---|------------|------------|
| V_{DS} | Drain-Source Voltage | 60 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_D @ T_A=25^\circ C$ | Continuous Drain Current, V_{GS} @ 10V ¹ | 15 | A |
| $I_D @ T_A=70^\circ C$ | Continuous Drain Current, V_{GS} @ 10V ¹ | 7.5 | A |
| I_{DM} | Pulsed Drain Current ² | 22 | A |
| EAS | Single Pulse Avalanche Energy ³ | 22 | mJ |
| I_{AS} | Avalanche Current | 23 | A |
| $P_D @ T_A=25^\circ C$ | Total Power Dissipation ⁴ | 1.5 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-ambient ¹ | --- | 85 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | --- | 25 | $^\circ C/W$ |

TM15N06SI

N-Channel Enhancement Mosfet

Electrical Characteristics (T_J=25°C unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Units |
|---|--|---|------|------|------|-------|
| Off Characteristic | | | | | | |
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | 60 | - | - | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =60V, V _{GS} = 0V, | - | - | 1.0 | μA |
| I _{GSS} | Gate to Body Leakage Current | V _{DS} =0V, V _{GS} = ±20V | - | - | ±100 | nA |
| On Characteristics | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 1.0 | 1.6 | 2.5 | V |
| R _{DS(on)} | Static Drain-Source on-Resistance note3 | V _{GS} =10V, I _D =5A | - | 30 | 40 | mΩ |
| | | V _{GS} =4.5V, I _D =3A | - | 36 | 50 | |
| Dynamic Characteristics | | | | | | |
| C _{iss} | Input Capacitance | V _{DS} =25V, V _{GS} =0V, f=1.0MHz | - | 1148 | - | pF |
| C _{oss} | Output Capacitance | | - | 58.5 | - | pF |
| C _{rss} | Reverse Transfer Capacitance | | - | 49.4 | - | pF |
| Q _g | Total Gate Charge | V _{DS} =30V, I _D =2.5A, V _{GS} =10V | - | 20.3 | - | nC |
| Q _{gs} | Gate-Source Charge | | - | 3.7 | - | nC |
| Q _{gd} | Gate-Drain("Miller") Charge | | - | 5.3 | - | nC |
| Switching Characteristics | | | | | | |
| t _{d(on)} | Turn-on Delay Time | V _{DS} =30V, I _D =5A, R _G =1.8Ω, V _{GS} =10V | - | 7.6 | - | ns |
| t _r | Turn-on Rise Time | | - | 20 | - | ns |
| t _{d(off)} | Turn-off Delay Time | | - | 15 | - | ns |
| t _f | Turn-off Fall Time | | - | 24 | - | ns |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| I _S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | 15 | A |
| I _{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | 20 | A |
| V _{SD} | Drain to Source Diode Forward Voltage | V _{GS} =0V, I _S =5A | - | - | 1.2 | V |
| t _{rr} | Body Diode Reverse Recovery Time | I _F =5A, dI/dt=100A/μs | - | 29 | - | ns |
| Q _{rr} | Body Diode Reverse Recovery Charge | | - | 43 | - | nC |

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : T_J=25°C, V_{DD}=30V, V_G=10V, L=0.5mH, R_G=25Ω, I_{AS}=8.7A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Performance Characteristics

Figure 1: Output Characteristics

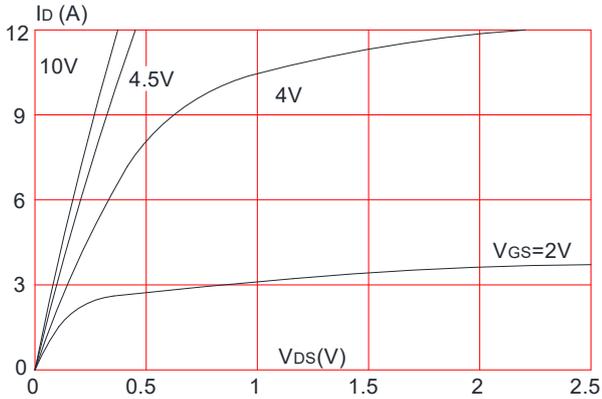


Figure 2: Typical Transfer Characteristics

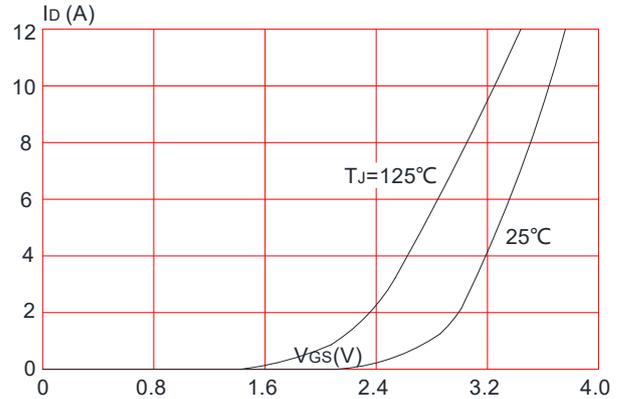


Figure 3: On-resistance vs. Drain Current

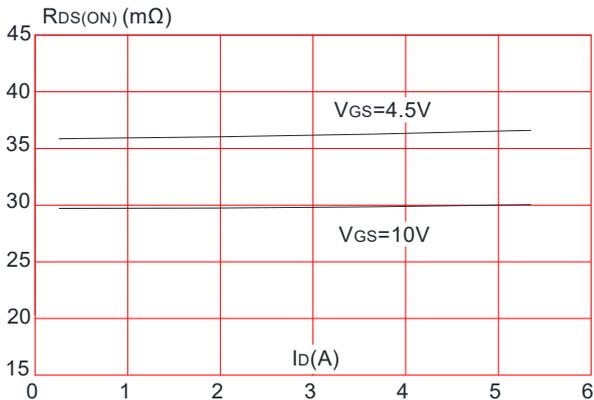


Figure 4: Body Diode Characteristics

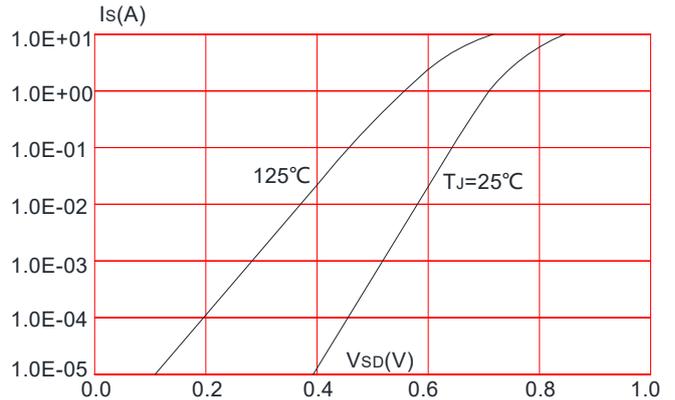


Figure 5: Gate Charge Characteristics

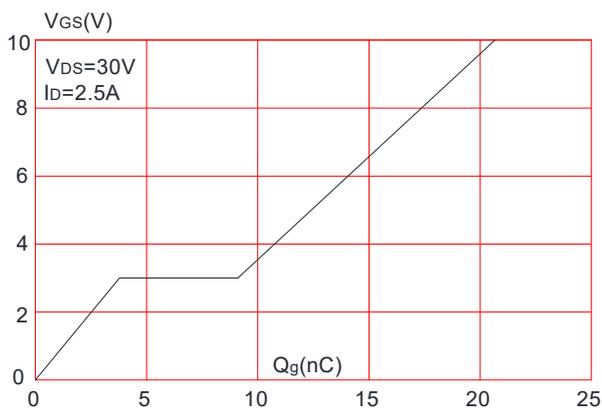
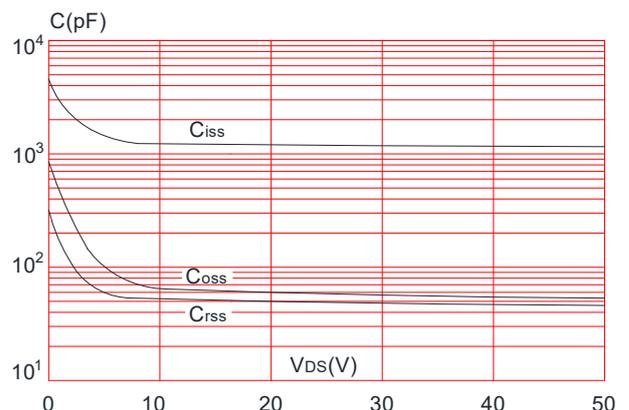


Figure 6: Capacitance Characteristics



TM15N06SI

N-Channel Enhancement Mosfet

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

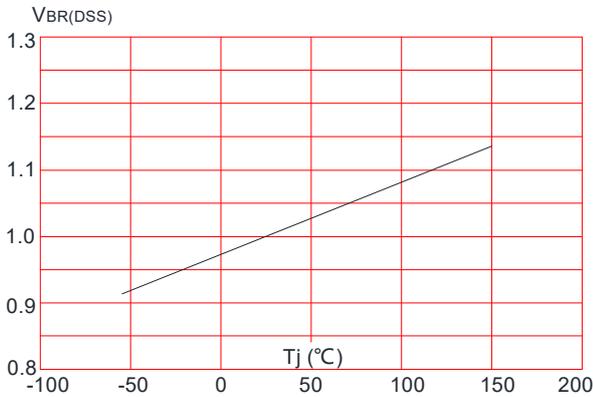


Figure 8: Normalized on Resistance vs. Junction Temperature

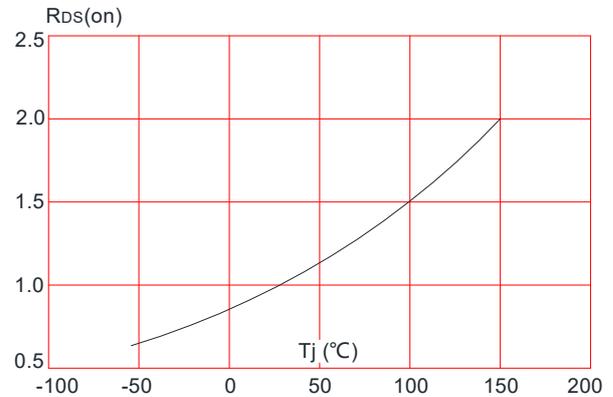


Figure 9: Maximum Safe Operating Area

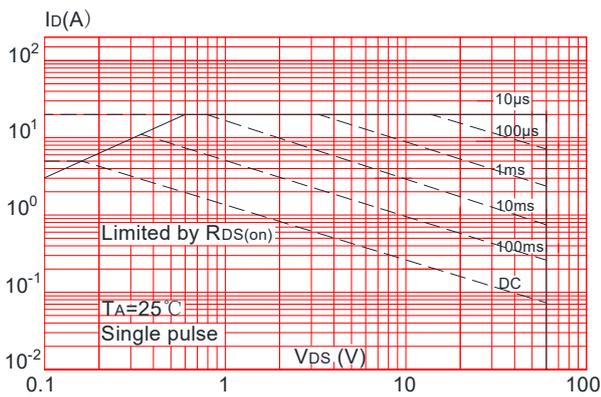


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

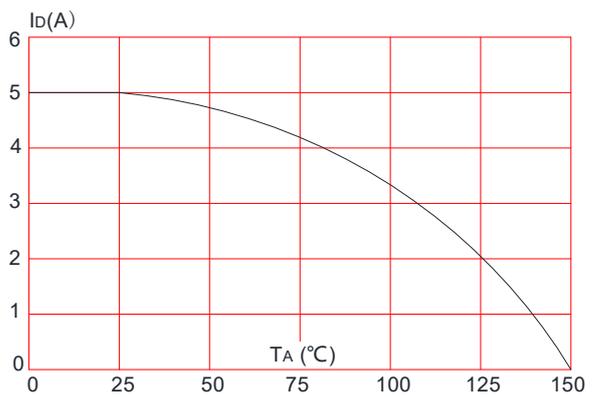
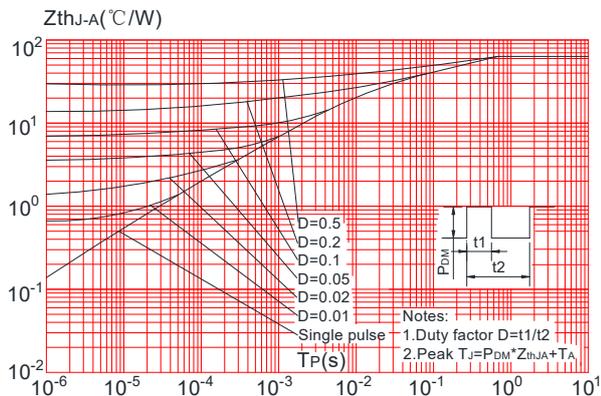
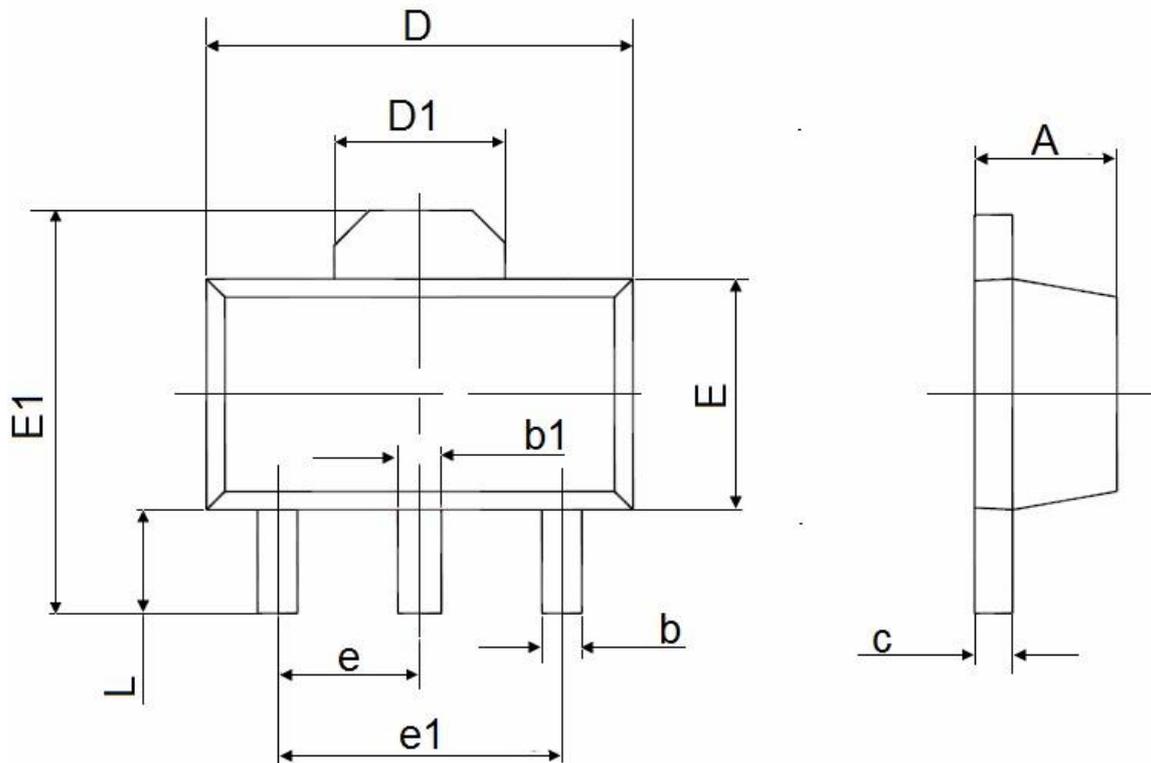


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



Package Mechanical Data:SOT-89-3L



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.400 | 1.600 | 0.055 | 0.063 |
| b | 0.320 | 0.520 | 0.013 | 0.020 |
| b1 | 0.400 | 0.580 | 0.016 | 0.023 |
| c | 0.350 | 0.440 | 0.014 | 0.017 |
| D | 4.400 | 4.600 | 0.173 | 0.181 |
| D1 | 1.550 REF. | | 0.061 REF. | |
| E | 2.300 | 2.600 | 0.091 | 0.102 |
| E1 | 3.940 | 4.250 | 0.155 | 0.167 |
| e | 1.500 TYP. | | 0.060 TYP. | |
| e1 | 3.000 TYP. | | 0.118 TYP. | |
| L | 0.900 | 1.200 | 0.035 | 0.047 |